ABSTRACT OF THE DISCLOSURE

PACKAGING AND INTERCONNECTION OF CONTACT STRUCTURE

A packaging and interconnection of a contact structure formed of a contact structure made of conductive material and formed on a contact substrate through a photolithography process, a contact trace formed on the contact substrate and electrically connected to the contact structure at one end, and the other end of the contact trace is provided with a contact pad for establishing packaging and interconnection from an upper surface thereof, a printed circuit board (PCB) pad provided on a printed circuit board (PCB) substrate to be electrically connected with the contact pad, a conductive lead for connecting the upper surface of the contact trace and the PCB pad, an elastomer provided under the contact substrate for allowing flexibility in the interconnection and packaging of the contact structure, and a support structure provided between the elastomer and the PCB substrate for supporting the contact structure, contact substrate and elastomer.

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